Moisture Sensitivity Level Rating Change for HMC487

Qualification Results Summary

MSL-3 Rating Change for HMC487 Device.

QUALIFICATION RESULTS			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULTS**
Solder Heat Resistance (SHR)*	JEDEC/ IPC J-STD-020	60	PASS
Temperature Cycling (TC)*	JEDEC JESD22-A104	175	PASS

*These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.